

## VERSION WITH MARKINGS TO SHOW CHANGES MADE

### In the Title

The Title has been amended as follows:

### METHOD OF MAKING A SEMICONDUCTOR PACKAGE DEVICE

### In the Abstract

The Abstract has been amended as follows:

**A method of making a semiconductor package device includes attaching a semiconductor chip to a metallic structure using an insulative adhesive, wherein the chip includes a conductive pad, the metallic structure includes first and second opposing surfaces and a conductive trace, the adhesive is disposed between the first surface and the chip, the conductive trace includes a recessed portion, a non-recessed portion and opposing outer edges between the first and second surfaces that extend across the recessed and non-recessed portions, and the recessed portion is recessed relative to the non-recessed portion at the second surface, forming an encapsulant that contacts the chip, the first surface, the outer edges and the recessed portion, wherein the encapsulant completely covers the chip, the outer edges and the recessed portion without completely covering the non-recessed portion, and forming a connection joint that electrically connects the conductive trace and the pad.**  
~~A semiconductor package device includes an insulative housing, a semiconductor chip, a terminal and a lead, wherein the insulative housing includes a top surface, a bottom surface, and a peripheral side surface between the top and bottom surfaces, the chip includes a conductive pad, the terminal protrudes downwardly from and extends through the bottom surface and is electrically connected to the pad, the lead protrudes laterally from and extends through the side surface and is electrically connected to the pad, the terminal and the lead are spaced and separated from one another outside the insulative housing, and the terminal and the lead are electrically connected to one another inside the insulative housing and outside the chip.~~

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**In the Specification**

The heading and paragraph at page 1, line 1 have been inserted as follows:

**CROSS-REFERENCE TO RELATED APPLICATIONS**

**This application is continuation of U.S. Application Serial No. 10/042,812 filed on January 9, 2002.**

**In the Claims**

Claims 1-60 have been canceled, and claims 61-140 have been added.

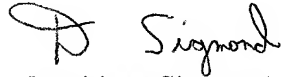
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## REMARKS

Claims 61-140 are pending. In this Preliminary Amendment, claims 1-60 have been canceled, and claims 61-140 have been added. In addition, the Title and Abstract have been revised to more clearly describe the claimed invention, and the Specification has been revised to cross-reference the parent case. No new matter has been added.

In view of the amendments and remarks set forth herein, the application is believed to be in condition for allowance. Should any issues remain, the Examiner is encouraged to telephone the undersigned attorney.

Respectfully submitted,



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